

Title (en)  
PROCESS FOR PRODUCING A LOCALLY HARDENED PROFILE COMPONENT

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES LOKAL GEHÄRTETEN PROFILBAUTEILS

Title (fr)  
PROCÉDÉ DE PRODUCTION D'UN COMPOSANT PROFILÉ DURCI LOCALEMENT

Publication  
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Application  
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Abstract (en)  
[origin: WO2008145327A1] The present invention relates to a process for producing a profile component (i) which at least in sections has a structurally increased strength from a semifinished sheet metal part (2), in which the semi-finished sheet metal part (2) is formed in an at least one-stage bending process and the bending process and also subsequent parting and cutting operations on the semifinished sheet metal part (2) are combined with a thermal treatment of at least one geometrically delineated region (A, C, D) of the semifinished sheet metal part (2), which comprises at least one heating step and a subsequent cooling step, in such a way that the at least one geometrically delineated region (A, C, D) has a structurally increased strength after cooling. Bending can be effected by means of roller profiling or swage bending. The rollers are preferably cooled.

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